

Title (en)  
JUNCTION BETWEEN A MICROSTRIP LINE AND A WAVEGUIDE

Title (de)  
ÜBERGANG ZWISCHEN EINER MIKROSTREIFENLEITUNG UND EINEM HOHLLEITER

Title (fr)  
JONCTION ENTRE UNE MICROBANDE ET UN GUIDE D'ONDES

Publication  
**EP 1540762 A1 20050615 (DE)**

Application  
**EP 03798047 A 20030730**

Priority  
• DE 0302553 W 20030730  
• DE 10243671 A 20020920

Abstract (en)  
[origin: DE10243671B3] The arrangement has a microstrip conductor on the upper side of a substrate and a hollow conductor on the upper side with an opening and a stepped structure on a side wall near the opening connected to the microstrip conductor. One hollow conductor side wall is a metallised coating on the substrate with an opening into which the microstrip conductor protrudes. Through contacting is arranged between rear metallisation and the metallised coating. The arrangement has a microstrip conductor (ML) on the upper side of a substrate and a hollow conductor on the upper side of the substrate with an opening and stepped structure (ST) on a side wall near the opening connected to the microstrip conductor, whereby one side wall of the hollow conductor is a metallised coating (LS) on the substrate with an opening into which the microstrip conductor protrudes. Through contacting (VH) is arranged between rear side metallisation (RM) enclosing the opening and the metallised coating on the upper side.

IPC 1-7  
**H01P 5/107**

IPC 8 full level  
**H01P 5/107** (2006.01)

CPC (source: EP KR US)  
**H01P 5/107** (2013.01 - EP KR US)

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)  
**US 2006145777 A1 20060706; US 7336141 B2 20080226**; AT E406672 T1 20080915; AU 2003257396 A1 20040419;  
AU 2003257396 B2 20080925; BR 0306449 A 20041026; CA 2499585 A1 20040408; CA 2499585 C 20110215; CN 100391045 C 20080528;  
CN 1682404 A 20051012; DE 10243671 B3 20040325; DE 50310414 D1 20081009; EP 1540762 A1 20050615; EP 1540762 B1 20080827;  
ES 2312850 T3 20090301; IL 167325 A 20100415; JP 2005539461 A 20051222; JP 4145876 B2 20080903; KR 100958790 B1 20100518;  
KR 20050057509 A 20050616; NO 20041694 L 20040427; PL 207180 B1 20101130; PL 374171 A1 20051003; WO 2004030142 A1 20040408

DOCDB simple family (application)  
**US 52843105 A 20051215**; AT 03798047 T 20030730; AU 2003257396 A 20030730; BR 0306449 A 20030730; CA 2499585 A 20030730;  
CN 03822218 A 20030730; DE 0302553 W 20030730; DE 10243671 A 20020920; DE 50310414 T 20030730; EP 03798047 A 20030730;  
ES 03798047 T 20030730; IL 16732505 A 20050308; JP 2004538686 A 20030730; KR 20057004819 A 20030730; NO 20041694 A 20040427;  
PL 37417103 A 20030730